


89. An electrochemical plating cell, comprising:  
a fluid basin having a fluid outlet;  
a substrate support assembly, comprising a plurality of radially positioned  
electrically conductive substrate contact pins positioned on an annular support member;  
and  
an anode assembly, comprising an ion source material positioned in a fluid  
permeable compartment having a fluid inlet positioned therein.

#### REMARKS

The Applicant requests that the Examiner enter the above noted amendments prior to examining the application. The amendments to the specification correspond to the corrections made in Applicant's Certificate of Correction dated May 28, 2002. Claims 1-29 were issued in U.S. Patent No. 6,261,433 and are submitted herewith. These claims have not been amended. New claims 30-89 have been added to allow the Applicant to claim more or less than the Applicant had the right to claim in the issued patent. Applicant submits that new claims 30-89 are supported by Applicant's specification as set forth in the accompanying Statement Under 37 C.F.R. 1.173(c) and do not constitute new matter. Applicant respectfully requests consideration and allowance of the application. The Examiner is invited to telephone the undersigned with any questions related to this application.

Respectfully submitted,



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